

PENDING CLAIMS:

The currently pending claims are provided, as follows:

- 1 1. An integrated circuit chip package comprising:
2 a metal substrate core including,
3 a first region, and
4 a second region electrically isolated from the first region.

- 1 2. The integrated circuit chip package of claim 1, wherein at least one of the regions
2 of the substrate core is coupled with an operating voltage rail of an integrated circuit chip.

- 1 3. The integrated circuit chip package of claim 1, wherein at least one of the regions
2 of the substrate core is coupled with a digital ground of an integrated circuit chip.

- 1 4. The integrated circuit chip package of claim 1, wherein at least one of the regions
2 of the substrate core is coupled with an analog ground of an integrated circuit chip.

- 1 5. The integrated circuit chip package of claim 1, wherein at least one of the regions
2 of the substrate core is coupled with an operating voltage rail of an integrated circuit chip,
3 and at least one other of the regions of the substrate core is coupled with a digital ground
4 of the integrated circuit chip.

- 1 6. The integrated circuit chip package of claim 1, wherein at least one of the regions
2 of the substrate core is coupled with an operating voltage rail of an integrated circuit chip,
3 and at least one other of the regions of the substrate core is coupled with an analog
4 ground of the integrated circuit chip.

- 1 7. The integrated circuit chip package of claim 1, wherein at least one of the regions
2 of the substrate core is coupled with a digital ground of an integrated circuit chip, and at
3 least one other of the regions of the substrate core is coupled with an analog ground of
4 the integrated circuit chip.

1 8. An integrated circuit chip package comprising:
2 a metal substrate core;
3 the metal substrate core having at least two electrically isolated regions;
4 wherein at least one of the electrically isolated regions of the metal substrate core
5 is coupled with a digital ground of an integrated circuit chip.

1 9. The integrated circuit chip package of claim 8, further comprising:
2 input and output signals of the integrated circuit chip routed through the
3 electrically isolated region of the metal substrate core that is coupled with the digital
4 ground of the integrated circuit chip.

1 10. The integrated circuit chip package of claim 9, wherein at least one other of the
2 electrically isolated regions of the metal substrate core is coupled with an operating
3 voltage rail of the integrated circuit chip.

1 11. The integrated circuit chip package of claim 9, wherein at least one other of the
2 electrically isolated regions of the metal substrate core is coupled with an analog ground
3 of the integrated circuit chip.

1 12. An integrated circuit chip package comprising:
2 a metal substrate core;
3 the metal substrate core having at least three electrically isolated regions;
4 wherein at least one of the electrically isolated regions of the metal substrate core
5 is coupled with a digital ground of an integrated circuit chip and has input and output
6 signals routed through it.

1 13. The integrated circuit chip package of claim 12, wherein at least one other of the
2 electrically isolated regions of the metal substrate core is coupled with an operating
3 voltage rail of the integrated circuit chip.